

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

RELEASE BY SECURED PARTY

CONVEYING PARTY DATA

Name	Execution Date
Hercules Technology II, L.P.	02/10/2009

RECEIVING PARTY DATA

Name:	Enpirion, Inc.
Street Address:	685 Route 202/206
City:	Bridgewater
State/Country:	NEW JERSEY
Postal Code:	06807

PROPERTY NUMBERS Total: 35

Property Type	Number
Application Number:	10985825
Application Number:	10985150
Application Number:	11244127
Application Number:	11243537
Application Number:	11243778
Application Number:	11243787
Application Number:	11368559
Application Number:	11584721
Application Number:	11852688
Application Number:	11852689
Application Number:	11852692
Application Number:	11852697
Application Number:	11852698
Application Number:	11852703
Application Number:	11852707

PATENT

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REEL: 022277 FRAME: 0935

OP \$1400.00 10985825

Application Number:	11852710
Application Number:	11852716
Patent Number:	7335948
Patent Number:	7330017
Patent Number:	7276998
Patent Number:	7256674
Patent Number:	7244994
Patent Number:	7232733
Patent Number:	7230302
Patent Number:	7229886
Patent Number:	7214985
Patent Number:	7195981
Patent Number:	7190026
Patent Number:	7186606
Patent Number:	7180395
Patent Number:	7144489
Patent Number:	7122105
Patent Number:	7038438
Patent Number:	7019505
Patent Number:	7015544

CORRESPONDENCE DATA

Fax Number: (866)369-2815

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 847-542-1858

Email: ebagarella@herculestech.com

Correspondent Name: Eileen Bagarella

Address Line 1: 934 Church Street

Address Line 4: Elmhurst, ILLINOIS 60126

NAME OF SUBMITTER:

Eileen M. Bagarella

Total Attachments: 6

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TERMINATION OF
PATENT SECURITY AGREEMENT

This Termination of the Intellectual Property Security Agreement (the "Termination"), dated as of February 10, 2009, is executed by Hercules Technology II, L.P., a Delaware limited partnership ("Secured Party") in favor of Enpirion, Inc., a Delaware corporation (the "Debtor").

RECITALS

WHEREAS, the Debtor and the Secured Party entered into a certain Loan and Security Agreement dated as of May 23, 2008 (the "Loan Agreement"); and

WHEREAS, in connection with Loan Agreement, the Debtor entered into a certain Intellectual Property Security Agreement dated as of May 23, 2008 (the "Assignment"); and

WHEREAS, pursuant to the Assignment, the Company granted to the Secured Party a security interest in certain Collateral (as defined in the Assignment) including certain intellectual property; and

WHEREAS, the Collateral in the Loan Agreement has been released, including all of the intellectual property described in the Assignment. Accordingly, the Assignment is terminated.

NOW, THEREFORE, the Secured Party agrees as follows:

1. The Secured Party is executing and delivering this Termination as evidence of the termination of the Assignment.
2. The Secured Party claims no right title or interest whatsoever in or to any of the Collateral described in the Assignment and the Secured Party expressly terminates its security interest in the intellectual property listed on Exhibit A hereto, which security interest was evidenced by the recordation of the Assignment with the United States Patent and Trademark Office.

IN WITNESS WHEREOF, this Termination is executed as of the first date written above.

HERCULES TECHNOLOGY II, L.P.,
a Delaware limited partnership

By: Hercules Technology SBIC Management,
LLC, its General Partner

By: Hercules Technology Growth Capital, Inc.,
its Manager

By: 
Name: K. Nicholas Martitsch

Its: Associate General Counsel

Exhibit A

Patents

18 US Patents Issued to Enpirion as of April 10, 2008.

- 1 7,335,948 Integrated circuit incorporating higher voltage devices and low voltage devices therein
- 2 7,330,017 Driver for a power converter and a method of driving a switch thereof
- 3 7,276,998 Encapsulated package for a magnetic device
- 4 7,256,674 Power module
- 5 7,244,994 Laterally diffused metal oxide semiconductor device and method of forming the same
- 6 7,232,733 Method of forming an integrated circuit incorporating higher voltage devices and low voltage devices therein
- 7 7,230,302 Laterally diffused metal oxide semiconductor device and method of forming the same
- 8 7,229,886 Method of forming an integrated circuit incorporating higher voltage devices and low voltage devices therein
- 9 7,214,985 Integrated circuit incorporating higher voltage devices and low voltage devices therein
- 10 7,195,981 Method of forming an integrated circuit employable with a power converter
- 11 7,190,026 Integrated circuit employable with a power converter
- 12 7,186,606 Method of forming an integrated circuit employable with a power converter
- 13 7,180,395 Encapsulated package for a magnetic device
- 14 7,144,489 Photochemical reduction of Fe(III) for electroless or electrodeposition of iron alloys
- 15 7,122,105 Use of siderophores to increase the current efficiency of iron plating solutions
- 16 7,038,438 Controller for a power converter and a method of controlling a switch thereof
- 17 7,019,505 Digital controller for a power converter employing selectable phases of a clock signal
- 18 7,015,544 Intergrated circuit employable with a power converter

19 Patent Applications Pending with USPTO

ENP	16	10/985,825	Method of Manufacturing an Encapsulated Package for a Magnetic Device	Pending 11/10/04
ENP	17	10/985,150	Method of Manufacturing a Power Module	Pending 11/10/04

ENP	18	11/244,127	Magnetic Device Having a Conductive Clip	Pending 10/5/05
ENP	19	11/243,537	Method of Forming a Magnetic Device Having a Conductive Clip	Pending 10/5/05
ENP	20	11/243,778	Power Module With a Magnetic Device Having a Conductive Clip	Pending 10/5/05
ENP	21	11/243,787	Method of Forming a Power Module With a Magnetic Device Having a Conductive Clip	Pending 10/5/05
ENP	22	11/368,559	Controller for a Power Converter and Method of Operating the Same	Pending 3/6/06
ENP	23	filed	Gate Drive Circuit	Pending 7/20/06
ENP	24	11/584,721	Controller Including Sawtooth Generator and Method of Operating the Same	Pending 10/20/06
ENP	25	11/852,688	MICROMAGNETIC DEVICE AND METHOD OF FORMING THE SAME	Pending 9/10/07
ENP	26	11/852,689	METHOD OF FORMING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	27	11/852,692	POWER CONVERTER EMPLOYING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	28	11/852,697	MICROMAGNETIC DEVICE AND METHOD OF FORMING THE SAME	Pending 9/10/07
ENP	29	11/852,698	METHOD OF FORMING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	30	11/852,703	POWER CONVERTER EMPLOYING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	31	11/852,707	ELECTROPLATING CELL AND TOOL	Pending 9/10/07
ENP	32	11/852,710	ELECTROLYTE AND METHOD OF PRODUCING THE SAME	Pending 9/10/07
ENP	33	11/852,716	METHODS OF PROCESSING A SUBSTRATE AND FORMING A MICROMAGNETIC DEVICE	Pending 9/10/07
ENP	34	11/965,618	POWER CONVERTER with Monotonic Turn-On for Pre-Charged Output Capacitor	Pending, Filed 12/17/2007

Trademarks

<u>Application No.</u>	<u>Mark</u>	<u>Final Status</u>
78314915	ENPIRION	Registered 8-02-05; Reg. No. 2,982,007
78315036	Empirion design	Registered 8-30-05; Reg. No. 2,990,452

BOI 15911543.1

Licenses

LICENSED PATENTS

1. Patent and Technology License Agreement, dated as of August 27, 2002, between Agere Systems Guardian Corporation, Agere Systems and Enpirion, as amended by Letter Agreement dated June 1, 2004. Below is a list of all IP licensed under such Agreement. Agere Systems is now LSI Corp.

U.S. PATENTS LICENSED FROM AGERE SYSTEMS, INC.:

<u>U.S. Patent No.</u>	<u>Title</u>
6,369,408	GaAs MOSFET Having Low Capacitance and On-Resistance
6,495,019	Device Comprising Micromagnetic Components for Power Applications
6,118,351	Micromagnetic Device for Power Processing Applications
6,160,721	Micromagnetic Device for Power Processing Applications
6,163,234	Micromagnetic Device for Data Transmission Applications
6,191,495	Micromagnetic Device Having an Anisotropic Core
6,255,714	Integrated Circuit Having a Micromagnetic Device Including a Ferromagnetic Core
6,005,377	Programmable Digital Controller for Switched Mode Power Conversion and Power Supply Employing the Same
6,038,163	Capacitor Loaded Memory Cell
6,272,039	Temperature Insensitive Capacitor Loaded Memory Cell
6,285,166	Battery Charger with Improved Overcharge Protection Mechanism and Method of Operation Thereof
6,285,223	Power Up Circuit for Analog Circuits
6,351,033	Multifunction Lead Frame and Integrated Circuit Package
6,573,818	Planar Magnetic Frame Inductors having Open Cores
6,541,819	A Semiconductor Device Having Non-Power Enhanced and Power Enhanced Metal Oxide Semiconductor Devices

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6,440,750	Method of Making Integrated Circuit having a Micromagnetic Device
6,682,962	GaAs MOSFET Having Low Capacitance and On-Resistance
6,903,373	SiC NMOSFET For Use As a Power Switch
7,021,518	Micromagnetic Device for Power Processing Applications**

** 09/484498 Abandoned by Agere; 7,021,518 issued as CIP on April 04, 2006. Application 387846 is a continuation of currently pending application Ser. No. 09/484,498, filed Jan. 18, 2000, Abandoned by Kossives, et al., and entitled "A Micromagnetic Device for Power Processing Applications And Method of Manufacture Therefor." The application Ser. No. 09/484,498 is a divisional of application Ser. No. 08/872,250, filed Jun. 10, 1997, which issued on Sep. 12, 2000, as U.S. Pat. No. 6,118,351 to Kossives, et al., and entitled "Micromagnetic Device for Power Processing Applications And Method of Manufacture Therefor." The above-listed application, Ser. No. 09/484,498 and U.S. Pat. No. 6,118,351, are commonly assigned with the present invention and are incorporated herein by reference

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